

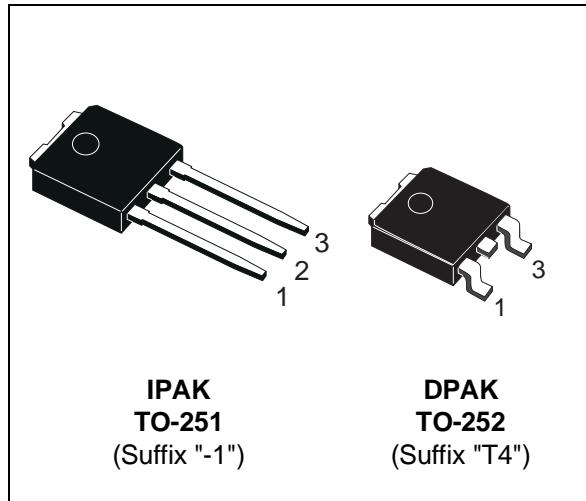
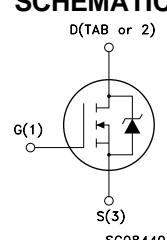
**STD9N10L****N - CHANNEL 100V - 0.22Ω - 9A IPAK/DPAK POWER MOS TRANSISTOR**

TYPE	V _{DSS}	R _{D(on)}	I _D
STD9N10L	100 V	< 0.27 Ω	9 A

- TYPICAL R_{D(on)} = 0.22 Ω
- AVALANCHE RUGGED TECHNOLOGY
- 100% AVALANCHE TESTED
- REPETITIVE AVALANCHE DATA AT 100°C
- HIGH CURRENT CAPABILITY
- 175°C OPERATING TEMPERATURE
- HIGH dV/dt RUGGEDNESS
- APPLICATION ORIENTED CHARACTERIZATION
- SURFACE-MOUNTING DPAK (TO-252) POWER PACKAGE IN TAPE & REEL (SUFFIX "T4")

APPLICATIONS

- HIGH CURRENT, HIGH SPEED SWITCHING
- POWER MOTOR CONTROL
- DC-DC & DC-AC CONVERTERS
- SYNCRONOUS RECTIFICATION

**INTERNAL SCHEMATIC DIAGRAM**

SC08440

ABSOLUTE MAXIMUM RATINGS

Symbol	Parameter	Value	Unit
V _{DS}	Drain-source Voltage (V _{GS} = 0)	100	V
V _{DGR}	Drain-gate Voltage (R _{GS} = 20 kΩ)	100	V
V _{GS}	Gate-source Voltage	± 20	V
I _D	Drain Current (continuous) at T _c = 25 °C	9	A
I _D	Drain Current (continuous) at T _c = 100 °C	6.4	A
I _{DM(•)}	Drain Current (pulsed)	36	A
P _{tot}	Total Dissipation at T _c = 25 °C	45	W
	Derating Factor	0.3	W/°C
dV/dt ₍₁₎	Peak Diode Recovery voltage slope	7	V/ns
T _{stg}	Storage Temperature	-65 to 175	°C
T _j	Max. Operating Junction Temperature	175	°C

(•) Pulse width limited by safe operating area

STD9N10L

THERMAL DATA

Rthj-case	Thermal Resistance Junction-case	Max	3.33	°C/W
Rthj-amb	Thermal Resistance Junction-ambient	Max	100	°C/W
Rthc-sink	Thermal Resistance Case-sink	Typ	1.5	°C/W
T _I	Maximum Lead Temperature For Soldering Purpose		275	°C

AVALANCHE CHARACTERISTICS

Symbol	Parameter	Max Value	Unit
I _{AR}	Avalanche Current, Repetitive or Not-Repetitive (pulse width limited by T _j max)	9	A
E _{AS}	Single Pulse Avalanche Energy (starting T _j = 25 °C, I _D = I _{AR} , V _{DD} = 25 V)	25	mJ

ELECTRICAL CHARACTERISTICS (T_{case} = 25 °C unless otherwise specified)

OFF

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
V _{(BR)DSS}	Drain-source Breakdown Voltage	I _D = 250 μA V _{GS} = 0	100			V
I _{DSS}	Zero Gate Voltage Drain Current (V _{GS} = 0)	V _{DS} = Max Rating V _{DS} = Max Rating x 0.8 T _c = 125 °C			10 100	μA μA
I _{GSS}	Gate-body Leakage Current (V _{DS} = 0)	V _{GS} = ± 15 V			± 100	nA

ON (*)

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
V _{GS(th)}	Gate Threshold Voltage	V _{DS} = V _{GS} I _D = 250 μA	1	1.7	2.5	V
R _{D(on)}	Static Drain-source On Resistance	V _{GS} = 5V I _D = 4.5 A V _{GS} = 10V I _D = 4.5 A T _c = 100°C		0.22 0.21	0.27 0.25	Ω Ω
I _{D(on)}	On State Drain Current	V _{DS} > I _{D(on)} x R _{D(on)max} V _{GS} = 5 V	9			A

DYNAMIC

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
g _{fs} (*)	Forward Transconductance	V _{DS} > I _{D(on)} x R _{D(on)max} I _D = 4.5 A	4	7		S
C _{iss} C _{oss} C _{rss}	Input Capacitance Output Capacitance Reverse Transfer Capacitance	V _{DS} = 25 V f = 1 MHz V _{GS} = 0		520 90 30	700 120 40	pF pF pF

ELECTRICAL CHARACTERISTICS (continued)

SWITCHING ON

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
$t_{d(on)}$ t_r	Turn-on Time Rise Time	$V_{DD} = 50 \text{ V}$ $R_G = 4.7 \Omega$ $I_D = 4.5 \text{ A}$ $V_{GS} = 5 \text{ V}$		10 25	14 35	ns ns
Q_g Q_{gs} Q_{gd}	Total Gate Charge Gate-Source Charge Gate-Drain Charge	$V_{DD} = 80 \text{ V}$ $I_D = 9 \text{ A}$ $V_{GS} = 10 \text{ V}$		13 5.5 6	18	nC nC nC

SWITCHING OFF

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
$t_{r(V_{off})}$ t_f t_c	Off-voltage Rise Time Fall Time Cross-over Time	$V_{DD} = 80 \text{ V}$ $R_G = 4.7 \Omega$ $I_D = 9 \text{ A}$ $V_{GS} = 5 \text{ V}$		10 10 25	14 14 35	ns ns ns

SOURCE DRAIN DIODE

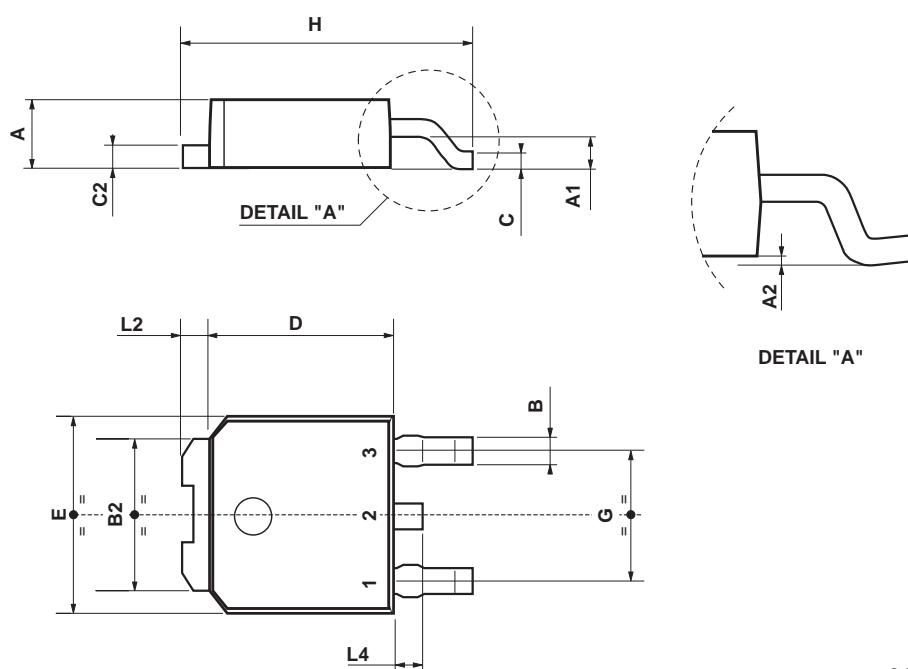
Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
I_{SD} $I_{SDM}(\bullet)$	Source-drain Current Source-drain Current (pulsed)				9 36	A A
$V_{SD} (\ast)$	Forward On Voltage	$I_{SD} = 9 \text{ A}$ $V_{GS} = 0$			1.5	V
t_{rr} Q_{rr} I_{RRM}	Reverse Recovery Time Reverse Recovery Charge Reverse Recovery Current	$I_{SD} = 9 \text{ A}$ $V_{DD} = 25 \text{ V}$ $di/dt = 100 \text{ A}/\mu\text{s}$ $T_j = 150 \text{ }^\circ\text{C}$		110 0.4 7.2		ns μC A

(*) Pulsed: Pulse duration = 300 μs , duty cycle 1.5 %

• Pulse width limited by safe operating area

TO-252 (DPAK) MECHANICAL DATA

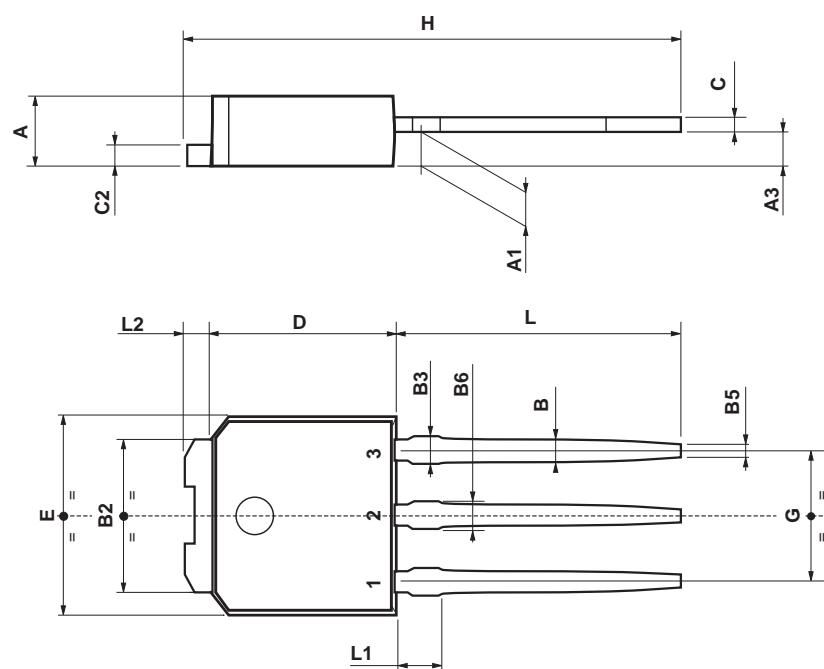
DIM.	mm			inch		
	MIN.	TYP.	MAX.	MIN.	TYP.	MAX.
A	2.2		2.4	0.086		0.094
A1	0.9		1.1	0.035		0.043
A2	0.03		0.23	0.001		0.009
B	0.64		0.9	0.025		0.035
B2	5.2		5.4	0.204		0.212
C	0.45		0.6	0.017		0.023
C2	0.48		0.6	0.019		0.023
D	6		6.2	0.236		0.244
E	6.4		6.6	0.252		0.260
G	4.4		4.6	0.173		0.181
H	9.35		10.1	0.368		0.397
L2		0.8			0.031	
L4	0.6		1	0.023		0.039



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TO-251 (IPAK) MECHANICAL DATA

DIM.	mm			inch		
	MIN.	TYP.	MAX.	MIN.	TYP.	MAX.
A	2.2		2.4	0.086		0.094
A1	0.9		1.1	0.035		0.043
A3	0.7		1.3	0.027		0.051
B	0.64		0.9	0.025		0.031
B2	5.2		5.4	0.204		0.212
B3			0.85			0.033
B5		0.3			0.012	
B6			0.95			0.037
C	0.45		0.6	0.017		0.023
C2	0.48		0.6	0.019		0.023
D	6		6.2	0.236		0.244
E	6.4		6.6	0.252		0.260
G	4.4		4.6	0.173		0.181
H	15.9		16.3	0.626		0.641
L	9		9.4	0.354		0.370
L1	0.8		1.2	0.031		0.047
L2		0.8	1		0.031	0.039



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